

Specifications Comparison Table of Mistubishi Laser Drilling System

| Subject | | ML605GTF (2-head,4-beam) | ML605GTF3 (2-head,4-beam) |
|----------------------------------|--|---|--|
| 設備基本介紹 Basic Introduction | 用途/功能 Function | 三菱CO2電路板雷射鑽孔機，使用三菱電機獨家的技術，達到封裝基板業界的頂級生產性，加工品質方面，加工較難加工的填料環氧樹脂也可有高品質、高精度的小孔徑加工成果。 Mitsubishi CO2 Laser Drilling System for PCB, using specific technology from Mitsubishi, can reach top productivity in panel sealing industry. As for the quality of manufacturing, even for more difficult manufacturing of epoxy resin can have high quality, high precision of small drilling holes effect. | 三菱CO2電路板雷射鑽孔機，使用三菱電機獨家的技術，達到封裝基板業界的頂級生產性，加工品質方面，加工較難加工的小孔徑加工成果。 Mitsubishi CO2 Laser Drilling System for PCB, using specific technology from Mitsubishi, can reach top productivity in panel sealing industry. As for the quality of manufacturing, even for more difficult manufacturing of epoxy resin can have high quality, high precision of small drilling holes effect. |
| 加工機 Laser machine | Table的大小 Table size | mm | 745x575 |
| | 加工範圍 Processing Workpiece dimension | mm | 620x560(包含固定式自動Galvano補正領域,F θ 鏡片掃描範圍,能量測定領域) 620x560(including fix auto Galvano compensation area, F θ lens scanned area, and power measurement area) |
| | Alignment Mark檢出範圍 Alignment Mark Detecting range | mm | 620x560 |
| | 行程 stroke | mm | 900x700x70 |
| | Table移送速度 Max. feed rate | m/min | 50 |
| | XYZ移動最小設定單位 Min. Movement of XYZ axis | mm | 0.001 |
| | 決定Table位置精度 Positioning accuracy | mm | 0.005/900(X)0.005/700(Y) |
| | Galvano掃描速度 Scanning frequency | point / sec | 1450 |
| | Galvano最大掃描範圍 Scan area(MAX) | mm | 25x25(High convergency f θ) |
| | 決定Galvano位置精度 Positioning accuracy | mm | ±0.015 |
| 發振器 Oscillator (CO2 laser) | 雷射型號 Model | | 5150U |
| | 雷射方式 Excitation | | CO2三軸直交 CO2 3-axis cross-flow |
| | 雷射波長 Wavelength | nm | 9300 |
| | 雷射定格出力 Rated power output | W | 150 |
| | 雷射脈衝周波數 Frequency setting range | Hz | 10~10000 |
| | 雷射脈衝幅 Width of pulse setting range | μ S | 4、16 |
| 控制裝置 Control function | NC裝置CPU NC-control CPU | | 64bit |
| | 畫像處理裝置 Image processing unit | | 內藏型 Buil-in |
| | 操作面板 Simplified operation screen | | 觸控式面板 Touch panel |
| 加工方式 Processing Method | 適合種類 Processing Type | | direct |
| 加工材料 Material | 適合材料 Material Type | | ABF材料 |
| 加工孔徑 Via diameter | 盲孔孔徑 Blind via diameter | direct | 50um以上 |
| | laser gas 交換時間 Time of exchange laser gas | | 48hr |
| | 電極 Electrodes | | 標準電極 |
| | 妨礙氣體sensor | | 無 N/A |
| | 安全性軟體 | | 無 N/A |